

Component & Substrate Attach

- Epoxy
 - Paste
 - Sheet / Preform
 - Silver Conductive
 - Non-Conductive
- Solder
 - Paste
 - Ribbon / Preform
 - Wire
- Automated and Manual systems

Wire Bond Capabilities

- Gold (Au) .001 to .002
- Aluminum (Al) .00125
- Automatic and Manual
 - Ball (0.0008" to 0.002" Gold)
 - Wedge (0.0007" to 0.002" Au & Al)
 - Ribbon (0.002" to 0.010")

